



THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Applicant:

Salman Akram

§

Art Unit: 2827

Serial No.: 09/853,111

§

Examiner: Alonzo Chambliss

Filed: May 10, 2001

§

Docket: MCT.0012D1US  
97-0141.02

For: Method of Fabricating Mounted  
Multiple Semiconductor Dies  
In a Package (As Amended)

§

**Mail Stop Non-Fee Amendment**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

**REPLY TO PAPER NO. 17**

Sir:

In response to the office action mailed October 20, 2003, reconsideration is requested in view of the following remarks.

Date of Deposit: November 26, 2003  
I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as **first class mail** with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

*Cynthia L. Hayden*  
Cynthia L. Hayden